



The semiconductor rendez-vous

PROVISIONAL PROGRAMME

Tuesday, October 8 Afternoon

- 13:00 Registration
- 14:00 Welcome speech
- 14:30 IPCEI ME/CT: what is it about?
- 14:45 IPCEI ME/CT: participants & topics
- 15:00 Companies' presentations
- Lynred, Soitec, STMicroelectronics
- 15:10 Microelectronics value chain & ecosystem
- Lynred, Soitec, STMicroelectronics
- 15:55 Break
- 16:40 Companies' presentations
- Renault, Valeo, Vitesco, XFAB
- 16:55 Power Electronics in an Electric Vehicle
- Renault, Valeo, Vitesco
- 17:25 Power electronics: requirements and technological challenges for low-cost, low-impact cars
- Renault
- 17:55 End of session

Wednesday, October 9 Morning

- 08:30 Welcoming participants
- 09:00 A Foundry Perspective for Automotive Applications & Solutions
- XFAB
- 09:30 *Panel discussion:* The contribution of innovation to the automotive market
- LYNRED, Renault, XFAB
- 10:00 Break
- 10:45 Companies' presentations
- Aledia, CEA, Murata
- 10:55 Power SiC & Power GaN
- Soitec, STMicroelectronics
- 11:25 Affordable thermal imaging for AEB - saving lives in all visibility conditions
- LYNRED
- 11:55 IPCEI overall result & Application to dashboard backlighting
- Aledia
- 12:25 Presentation of 4 Czech companies in relation with IPCEI ME/CT
- Cudasip, Mycroft Mind, NXP, UJP PRAHA
- 13:00 Lunch

Wednesday, October 9 Afternoon

14 :15	Welcoming participants		
14:30	From Moore's law to 3D integration <ul style="list-style-type: none">• STMicroelectronics France	14:30	Technical presentation of main results from a collaboration with a Direct Partner <ul style="list-style-type: none">• STMicroelectronics Italy
15 :00	Integrated Silicon Capacitor: Optimization of the performances of advanced processors by using a combination of advanced packaging technologies and ultrathin silicon capacitors <ul style="list-style-type: none">• Murata	15 :00	POI, RF & InP from 5G to 6G: standardization challenges <ul style="list-style-type: none">• Soitec
15 :30	Break		
16:00	Advanced Technology for automotive packaging <ul style="list-style-type: none">• STMicroelectronics Malta	16:00	Next Generation FDSOI, 3D solution and Photonics: AI challenges, Smart Devices <ul style="list-style-type: none">• Soitec
16:30	18 nm FDSOI with ePCM <ul style="list-style-type: none">• STMicroelectronics France	16:30	Power electronics platform <ul style="list-style-type: none">• Vitesco
17:00	Visit to IPCEI partners' stands		
17:30	End of session		
19:00	Gala dinner: You are cordially invited to the Vikarka Restaurant. Please arrive at 19:00 sharp!		
23 :00	End of Gala dinner		

Thursday, October 10 Morning

- 08:30 Welcoming participants
- 09:00 European collaborative projects framework
- STMicroelectronics
- 09:15 Example of European collaborative projects
- CEA, Soitec, others
- 09:45 *Panel discussion:* Environmental challenges linked to IPCEI issues
- CEA, Murata, Soitec, Vitesco
- 10:15 Break
- 11:00 *Panel discussion:* Training in microelectronics, job opportunities, matching companies' recruitment needs
- CNSC, Czech Technical University in Prague, STMicroelectronics Italy
- 11:30 *Panel discussion:* IPCEI ME/CT Spillovers, a great opportunity for the benefits of EU enterprises, academics & students
- Continental
- 12:00 Conclusion
- CNSC, Minalogic
- 12:15 Visit to IPCEI partners' stands
- 13:00 Lunch
- 14:30 End of the event